

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-5 (canceled).

Claim 6 (new): An electronic component device comprising:

a rectangular plate-shaped element including a functional part and a first frame-shaped electrode surrounding the functional part, wherein the coefficient of linear expansion in the x direction along a side of the rectangle is different from the coefficient of linear expansion in the y direction orthogonal to the x direction in the rectangular plane;

a substrate including a second frame-shaped electrode arranged on a front face of the substrate at a position so as to correspond to the first frame-shaped electrode; and

a solder sealing frame provided on the surface of at least one of the first frame-shaped electrode and the second frame-shaped electrode; wherein

each of the first frame-shaped electrode, the second frame-shaped electrode, and the solder sealing frame includes a strip-shaped portion extending in the x direction and a strip-shaped portion extending in the y direction;

the element and the substrate are bonded together with the solder sealing frame, the functional part provided on the element is hermetically sealed in a space formed between the element and the substrate; and

when the difference in expansion in the x direction between the element and the substrate is represented by  $Q_x$  and the difference in expansion in the y direction between the element and the substrate is represented by  $Q_y$ , in each of the first frame-shaped electrode, the second frame-shaped electrode, and the solder sealing frame, a width of the strip-shaped portion extending in the direction having the larger difference in expansion is smaller than a width of the strip-shaped portion extending in the direction having the smaller difference in expansion.

Claim 7 (new): The electronic component device according to claim 6, wherein the thickness of the solder sealing frame is about 18  $\mu\text{m}$  or more.

Claim 8 (new): The electronic component device according to claim 6, wherein when the coefficient of linear expansion in the x direction of the substrate is represented by  $A_x$ , the coefficient of linear expansion in the y direction of the substrate is represented by  $A_y$ , the coefficient of linear expansion in the x direction of the element is represented by  $B_x$ , the coefficient of linear expansion in the y direction of the element is represented by  $B_y$ , the length of the external side of the strip-shaped portion extending in the x direction of the first and second frame-shaped electrodes is represented by  $dl_x$ , the length of the external side of the strip-shaped portion extending in the y direction of the first and second frame-shaped electrodes is represented by  $dl_y$ , the difference  $Q_x$  in expansion is represented by  $Q_x = |A_x - B_x| \times dl_x$  (mm/ $^{\circ}\text{C}$ ), and the difference  $Q_y$  in expansion is represented by  $Q_y = |A_y - B_y| \times dl_y$  (mm/ $^{\circ}\text{C}$ ), then the larger difference in expansion is about  $2.2 \times 10^{-5}$  (mm/ $^{\circ}\text{C}$ ) or less.

Claim 9 (new): The electronic component device according to claim 6, wherein when the ratio of flexural rigidity in the x direction between the element and the substrate is represented by  $R_x$  and the ratio of flexural rigidity in the y direction between the element and the substrate is represented by  $R_y$ , the larger ratio of the flexural rigidity ratios  $R_x$  and  $R_y$  is about 1.2 or less.

Claim 10 (new): The electronic component device according to claim 6, wherein the element is a surface acoustic wave element.

Claim 11 (new): The electronic component device according to claim 6, wherein the element is a high frequency element.

Claim 12 (new): An electronic component device comprising:  
a rectangular plate-shaped element including a functional part and a first frame-shaped electrode, wherein the coefficient of linear expansion in the x direction along a side of the rectangle is different from the coefficient of linear expansion in the y direction orthogonal to the x direction in the rectangular plane; and

a substrate including a second frame-shaped electrode; wherein each of the first frame-shaped electrode and the second frame-shaped electrode includes a strip-shaped portion extending in the x direction and a strip-shaped portion extending in the y direction;

the element and the substrate are bonded together with the functional part provided on the element hermetically sealed in a space formed between the element and the substrate; and

when the difference in expansion in the x direction between the element and the substrate is represented by  $Q_x$  and the difference in expansion in the y direction between the element and the substrate is represented by  $Q_y$ , in each of the first frame-shaped electrode and the second frame-shaped electrode, a width of the strip-shaped portion extending in the direction having the larger difference in expansion is smaller than a width of the strip-shaped portion extending in the direction having the smaller difference in expansion.